

## EHS6



Five Band 3G  
HSPA



Quad Band  
GPRS / EDGE  
Class 12



Multi Design  
Capability  
(LGA)



Java  
embedded



USB 2.0  
High Speed  
compatible



Advanced  
Temperature  
Management



Embedded  
TCP/IP Stack



RLS Monitoring  
(Jamming Detection)



FOTA  
configurable &  
royalty-free



## 3G

**Cinterion® EHS6 Wireless Module**  
**Global 3G with Java™ embedded**

# Cinterion® EHS6 Wireless Module

## Global 3G with Java™ Embedded

The flagship Cinterion® EHS6 is the 5<sup>th</sup> generation of Gemalto M2M's Java embedded machine-to-machine (M2M) modules, which have simplified highly efficient, end-to-end industrial communication for the last decade. Gemalto's Java strategy enables customers and partners to leverage the massive Java ecosystem by offering a powerful ARM11 architecture to reduce complexity and speed application integration. The tiny EHS6 module offers the latest Java ME 3.2 client runtime platform optimized for resource-constrained M2M applications. It significantly reduces total cost of ownership (TCO) and time to market by sharing internal resources such as memory, a large existing code base and proven software building blocks.

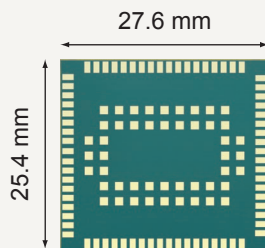
The improved Java concept uses Multi MIDlet Java execution to simultaneously host and run multiple applications and protocols. An extended security concept with the latest TLS/SSL engine provides secure and reliable TCP/IP connectivity while an enriched internal flash file system enables royalty free firmware updates over-the-air (FOTA) when required. Sophisticated sandbox modeling and layered architectures simplify device management (DM) and separate mobile

network operator approvals from application code development, allowing simultaneous progress of both phases for a shorter time to market.

Providing the capability for multiple designs from one solution, the newest addition to Gemalto M2M's Evolution platform is an ideal module for M2M applications migrating from 2G to 3G that require cost efficiency along with global connectivity. EHS6 offers five band HSPA to support high bandwidth connectivity, enabling speeds up to 7.2 Mbps in downlink and 5.7 Mbps in uplink and rounds out the existing portfolio comprised of the Evolution platform.

EHS6 comes in Gemalto M2M's unique Land Grid Array (LGA) package perfectly suited to the manufacturing needs of small, high-volume M2M devices with a focus on reliable and efficient processes. The ultra compact hardware design incorporates minimal power consumption, optimized heat dissipation even under harsh operating conditions and an extended product lifecycle to guarantee long product availability. EHS6 supports common industrial interfaces such as USB, serial interfaces, I<sup>2</sup>C and various GPIO's to be connected with the Java engine.

### Global 3G with Java™ Embedded



#### LGA technology

Land grid array, or LGA, is a surface-mount technology for fully automated manufacturing allowing to benefit from efficiency and process consistency. Gemalto M2M's unique type of LGA technology is designed with focus on highest reliability and flexibility and to meet the demanding requirements of M2M application manufacturers.

#### Full type approval

As is true with all Cinterion modules, EHS6 includes full type approval (FTA) for global roaming as well as certification from the largest mobile operators worldwide.

#### Java™

Java offers easy and fast application development, a broad choice of tools, high code reusability, easy maintenance, a proven security concept, on-device debugging as well as multi-threading programming and program execution.

#### Gemalto M2M Support includes:

- > Personal design-in consulting for hardware and software
- > Extensive RF test capabilities
- > GCF/PTCRB conform pretests to validate approval readiness
- > Regular training workshops



Local engineers, a competent helpdesk, a dedicated team of R&D specialists and an advanced development center are the hallmarks of our leading support offer.

# Cinterion® EHS6 Features

## GENERAL FEATURES

- > 3GPP Rel.7 Compliant Protocol Stack
- > Five Bands UMTS (WCDMA/FDD)  
Bands: 800, 850, 900, 1900 and 2100 MHz
- > Quad-Band GSM  
Bands: 850, 900, 1800 and 1900 MHz
- > SIM Application Toolkit, letter class "b", "c", "e"
- > Control via standardized and extended ATcommands (Hayes, TS 27.007 and 27.005)
- > TCP/IP stack access via AT command and transparent TCP services
- > Secure Connection for client IP services
- > Internet Services TCP/UDP server/client, DNS, Ping, FTP client, HTTP client
- > Supply voltage range 3.3 - 4.5 V, highly optimized for minimal power consumption
- > Dimension: 27.6 x 25.4 x 2.3 mm
- > Weight: 3 g
- > Operating Temperature: -40 °C to +90 °C

## SPECIFICATIONS

- > HSDPA Cat.8 / HSUPA Cat.6 data rates  
DL: max. 7.2 Mbps, UL: max. 5.76 Mbps
- > EDGE Class 12 data rates  
DL: max. 237 kbps, UL: max. 237 kbps
- > GPRS Class 12 data rates  
DL: max. 85.6 kbps, UL: max. 85.6 kbps
- > CSD data transmission up to 9.6 kbps, V.110, non-transparent
- > SMS text and PDU mode support
- > High quality voice support for handset, headset and hands-free operation
- > Integrated TTY modem
- > Speech codec: FR, HR, EFR and AMR

## SPECIAL FEATURES

- > USB interface supports multiple composite modes and a Linux-/Mac- compliant mode
- > Firmware update via USB and serial interface
- > Real time clock with alarm functionality
- > Multiplexer according 3GPP TS 27.010
- > RLS Monitoring (Jamming detection)
- > Informal Network Scan
- > Customer IMEI/SIM-Lock as variant
- > Integrated FOTA, configurable and royalty free

## JAVA OPEN PLATFORM

- > Java™ ME 3.2
- > Secure data transmission with HTTPS/SSL
- > Multi-Threading programming and Multi-Application execution
- > 6 MB RAM and 10 MB Flash File System

## INTERFACES (LGA PADS)

- > Pad for GSM/WCDMA Antenna
- > USB 2.0 HS interface up to 480 Mbps
- > High speed serial modem interface ASC0
- > HSIC HS interface up to 480 Mbps
- > 16 GPIO lines shared with DSR, DTR, DCD (all ASC0), ASC1 (RXD, TXD, RTS, CTS), SPI, Fast-Shutdown, Network-Status-Indication, PWM and Pulse-Counter lines
- > ADC and I<sup>2</sup>C interface
- > 4-wire high speed serial interfaces ASC1
- > Digital audio interface
- > UICC and U/SIM card interface 1.8 V / 3 V
- > Lines for Module-On and Reset

## DRIVERS

- > USB, MUX driver for Microsoft® Windows XP™, Vista™ and 7™
- > RIL, USB driver for Microsoft® Windows Embedded Handheld™ >= 6.x
- > USB, MUX driver for Microsoft® Windows Embedded Compact™ >= 5.x

## APPROVALS

- > R&TTE, GCF, CE, FCC, PTCRB, IC, UL
- > AT&T and other local approvals and provider certifications
- > EuP, RoHS and REACH compliant

**For more information, please visit**

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security to be free